

Programmes After Market Services

NPL-1 Series Cellular Phones

3 – Audio System

Table of Contents

| Description | Page No. |
|---|----------|
| Introduction | 5 |
| Abbreviations | 5 |
| Technical overview | 6 |
| Block diagram | 6 |
| Parts list | 7 |
| DC characteristics | 8 |
| Audio function description | 8 |
| Audio control | 8 |
| Gain table | 9 |
| Internal audio devices | 10 |
| Earpiece | 10 |
| Earpiece acoustic design | 11 |
| Earpiece electrical interface | 13 |
| Microphone | 14 |
| Sketch of microphone acoustic design | 15 |
| Microphone electrical interface | 16 |
| Buzzer | 17 |
| Buzzer acoustic design | 18 |
| Buzzer electrical interface | 19 |
| Vibra specification | 20 |
| Vibra electrical interface | 20 |
| External audio devices | 21 |
| Audio accessories | 21 |
| External audio interface | 24 |
| External audio interface - electrical interface | 24 |
| External audio connector | 28 |
| External audio signal electrical specification | 29 |
| Accessory detection, identification and control | 31 |
| Accessory detection | 31 |
| Accessory identification | 31 |
| Accessory control | 32 |

List of Figures

| | | |
|----------|---|----|
| Figure 1 | Audio block diagram | 6 |
| Figure 2 | Sketch of earpiece acoustic design | 11 |
| Figure 3 | Mechanical assembly of earpiece and vibra | 12 |
| Figure 4 | Earpiece frequency response - ERP corrected - non DSP corrected | 11 |
| Figure 5 | DAI receiving frequency response, B4.0 | 13 |
| Figure 6 | Internal earpiece electrical interface | 13 |
| Figure 7 | Microphone acoustical design | 15 |
| Figure 8 | DAI sending frequency response, B4.0 | 15 |
| Figure 9 | Internal microphone electrical interface | 16 |

| | Description | Page No. |
|------------------------------------|--|----------|
| List of Figures (continued) | | |
| Figure 10 | Sketch of buzzer acoustic design | 18 |
| Figure 11 | Mechanical buzzer assembly | 18 |
| Figure 12 | Typical buzzer frequency response | 18 |
| Figure 13 | Buzzer driver circuit | 19 |
| Figure 14 | Vibra driver circuit | 20 |
| Figure 15 | External microphone interface | 25 |
| Figure 16 | External earpiece interface | 27 |
| Figure 17 | System connector - mechanical outline | 29 |
| Figure 18 | Carokit audio interface. block diagram | 33 |

List of Tables

| | | |
|----------|---|----|
| Table 1 | Parts list | 7 |
| Table 2 | Supply voltages | 8 |
| Table 3 | Possible UEM gains for each input and output | 9 |
| Table 4 | Total UEM gain for each input and output in different audio paths | 9 |
| Table 5 | UEM ear output specification | 14 |
| Table 6 | Microphone input specifications | 17 |
| Table 7 | Buzzer driver specifications | 19 |
| Table 8 | Vibra driver specifications | 21 |
| Table 9 | Vibra output frequency control | 21 |
| Table 10 | HDC-9P interface specifications | 22 |
| Table 11 | Selected specifications for HDW-1 BT headset | 22 |
| Table 12 | LPS-1 interface specifications | 23 |
| Table 13 | Microphone input specifications, external audio | 26 |
| Table 14 | UEM HF output specifications | 27 |
| Table 15 | System connector pin assignment | 29 |
| Table 16 | HEADINT voltage value table used for accessory identification | 31 |

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Introduction

This Chapter specifies the Audio hardware for the NPL-1 program.

Abbreviations

| | |
|-----------|---|
| UEM | Universal Energy Management |
| UPP | Universal Phone Processor |
| UIF codec | User InterFace Codec in UPP |
| VBAT | Main battery voltage |
| PWM | Pulse Width Modulated (signal) |
| MUX | MUltiPlexer |
| GND | Phone ground |
| LGND | GND abbreviation in System connector |
| SGND | Signal ground – reference for microphone |
| MCU | MicroController Unit |
| PWB | Printed Wire Board |
| ERP | Ear Reference Point |
| MRP | Mouth Reference Point |
| SPL | Sound Pressure Level (reference value 20 uPa) |
| BT | BlueTooth |
| AGC | Adaptive Gain Control |
| DRC | Dynamic Range Compressor |
| ALWE | Noise suppressor algorithm |
| AEC | Acoustic Echo Canseler |
| IMD | Insert Moulded Decoration |
| SCO | Synchronous Connection Oriented |
| LPRF | Low Power Radio Frequency (BlueTooth) |
| PWM | Pulse Width Modulated |

Technical overview

Block Diagram

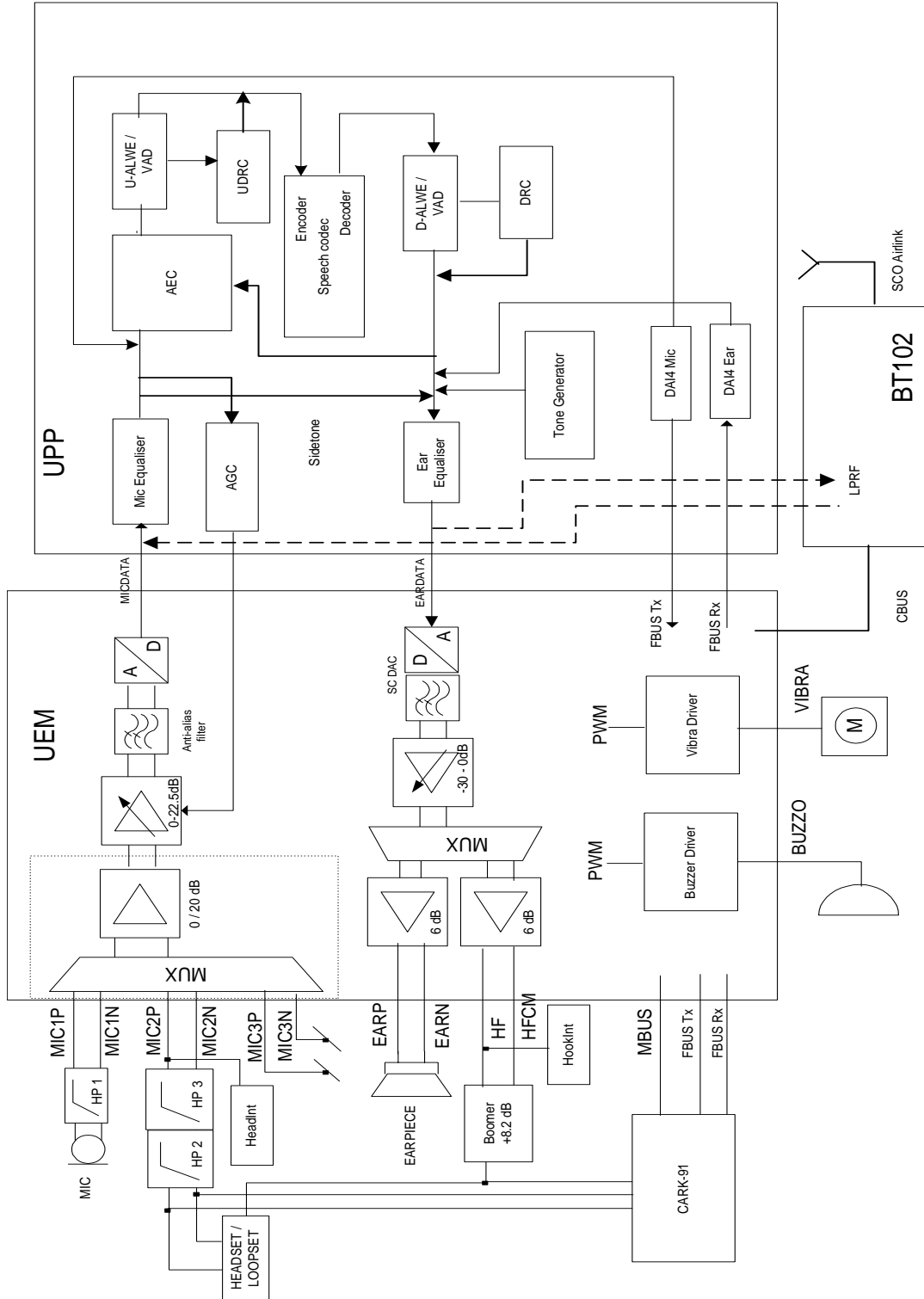


Figure 1. Audio Block diagram

Part List

All involved key parts are listed in the following table. As seen in the table there is only one vendor for some of the audio and vibration key components.

Table 1: Parts list

| NAME OF THE SUB-MODULE | COMPONENT DESIGNATION | VENDOR | MATERIAL CODE |
|---|--|--------------------------|---------------|
| Buzzer 1 | MCC-03ACS | STAR | 5140209 |
| Earpiece 2 | TYPE: WD 00518/32 U CODE: 2403 252 08108 | PHILIPS Earpiece Systems | 5140067 |
| Earpiece 1 | LT 201 | KIRK Acoustics | 5140233 |
| Microphone assy 1 | WM-64-HNY-310 | MATSUSHITA | 5140225 |
| Vibrator 1 | KHN4NB1H | MATSUSHITA | 6800043 |
| Headset | HDC 9P | NMP | |
| Loopset | LPS-1 | NMP | |
| Carkit - Handsfree unit - Handsfree earpiece - Microphone - Handset unit | CARK-91 - HFU-2 - HFS-12 - HFM-8 - HSU-1 | NMP | |
| Bluetooth Carkit - Junction box - Remote control button - Handsfree earpiece - Microphone - Handset unit | CARK-112 - HFW-1 - CUW-2 - HFS-12 - HFM-8 - HSU-1 | NMP | 0750135 |
| Bluetooth headset | HDW-1 | NMP | 0694064 |
| UEM | | | 4370805 |
| UPP | | | 4370815 |
| Boomer | LM4890 | National semiconductors | 4341221 |
| System connector | | | 5469061 |

DC Characteristics

The audio relevant supply voltages are shown in the following table:

Table 2: Supply Voltages

| Line Symbol | Minimum | TYP. / Nominal | Maximum | Unit | Notes |
|-------------|------------------------|----------------|------------------------|------|---|
| Vana | 2.7 | 2.78 | 2.86 | V | (Mic bias buffer) |
| | 0,005 | | 80 | mA | Min. due to regulator stability |
| VBAT | 3.1 (SW) (2.9 (HW)) | 3.6 | 5.1 (SW) (5.4 (HW)) | V | (Buzzer and Vibra driver). Min and max due to SW cut off. |
| Vflash1 | 2.7 | 2.78 | 2.86 | V | (DLR3, HEADINT and HOOKINT pull up) |
| | 0.005 | | 70 | mA | Min. due to regulator stability |
| | 0.005 | | 1.5 | mA | Sleep |
| Vflash2 | 2.7 | 2.78 | 2.86 | V | (DLR3) |
| | 0.005 | | 40 | mA | Min. due to regulator stability |
| VIO | 1.72 | 1.8 | 1.88 | V | (HOOKINT level shifter) |

Audio Function Description

Audio control

The audio control and processing is done by the UEM, which contains the audio codec and the UPP contains DSP blocks, handling and processing the audio data signals.

The audio block diagram is presented in , page 3-6.

The UEM supports three microphone inputs and two earphone outputs. The inputs can be taken from an internal microphone, a headset microphone or a handsfree-unit / Carkit microphone. The microphone signals from different sources are connected to separate inputs at the UEM ASIC. Inputs for the microphone signals are differential type.

MIC1 and EAR in/output are used for the internal microphone input and Earpiece output. The Headset or handsfree unit / Carkit audio is connected to the MIC2 input / HF (single ended) output. The MIC3/XEAR is connected to GND and not used in the NPL-1 project.

Input and output selection and gain control is performed inside the UEM ASIC (register AudioCtrl (Gain and routing) and MicBias (microphone bias selection)).

Additional gain is added in the DSP SW. This gain is controlled by adaptive algorithms (AGC, DRC, ALWE and AEC) and set as a function of background noise, signal level and echo canceling.

In case of BT audio the BT accessory and the phone is connected by both an ACL and SCO air link. ACL is used for connection commands and SCO for the actual audio transmission. In both cases the BT module (in accessory and phone) receives the audio signal. In the phone this signal is routed from BT module over LPRF to DSP where it follows the regular audio path through out the rest of the system. The BT module and MCU is connected by the CBUS for exchanging low level information.

All BT Gain adjustments are done in the accessory. DSP tuning is done in UPP, completely as usually.

Gain Table

The possible gain for each input and output is shown in The gain settings are controlled in the 16 bit AudioCtrlR register. Note * MIC3 only used for test purposes in NPL-1.. Table 4: Total UEM gain for each input and output in different audio paths (modes). contains the total gain for each input and output in different audio modes.

The gain settings are controlled in the 16 bit AudioCtrlR register.

Table 3: Possible UEM gains for each input and output

| UEM Pins | Gain (dB) | | |
|-------------------|-----------------------|--------------|-------------------------------------|
| | Input / Output | Programmable | Fixed UEM |
| MIC1 | 0 to 22.5, step 1.5dB | 20 | 20 to 42.5, step 1.5dB |
| MIC2 | 0 to 22.5, step 1.5dB | 0 or 20 | 0 to 22.5 or 20 to 42.5, step 1.5dB |
| MIC3* | 0 to 22.5, step 1.5dB | 0 or 20 | 0 to 22.5 or 20 to 42.5, step 1.5dB |
| HF (single ended) | -30 to 0, step 2dB | 6 | -24 to 6, step 2dB |
| EAR | -30 to 0, step 2dB | 6 | -24 to 6, step 2dB |

Note * MIC3 only used for test purposes in NPL-1.

Table 4: Total UEM gain for each input and output in different audio paths (modes)

| Gain Table | | Normal Mode - Gain dB | | |
|------------|------------------|------------------------|-----------------------|----------------------|
| | UEM Signals ↓ | Handportable | Headset | Handsfree (Carkit) |
| INPUTS | MIC1 | 20 to 42.5, step 1.5dB | | |
| | MIC2 | | 20 to 42.5 step 1.5dB | 0 to 22,5 step 1.5dB |
| | MIC3 | | | |
| OUTPUTS | EAR | -24 to 6, step 2dB | | |
| | HF | | -24 to 6, step 2dB | -24 to 6, step 2dB |

Deviations in gain performance:

Transmit gain absolute accuracy: -1.0 / 0.0 dB

Transmit gain variation (temperature, supply): +/- 0,7 dB

| | |
|---|---------------------------------------|
| Transmit gain variation with frequency (300 – 3000 Hz): | +/- 0,5 dB |
| Transmit gain variation with signal level (> -50 dBm0): | +/- 0,5 dB (<-50 dBm0: +/- 1.2 dB) |
| Receive gain absolute accuracy: | +/- 0,5 dB |
| Receive gain variation (temperature, supply): | +/- 0,7 dB |
| Receive gain variation with frequency (100 – 3000 Hz): | +/- 0,5 dB |
| Receive gain variation with signal level (> -50 dBm0): | +/- 0,5 dB (<-50 dBm0: +/- 1.2 dB) |

DSP Gain:

Initially the DSP gain uplink (Mic) is set to 12 dB and 0 dB downlink. This is done in the Equaliser.

The AGC controlled by the DSP is able to reduce the Uplink gain in the UEM by 18 dB maximum in steps of 1.5 dB.

The DRC can either attenuate the signal or enhance in it in DSP by up to 10 dB.

Note: Local mode gains are optimised for production testing and are not the same as in normal mode.

Internal Audio Devices

NPL-1's internal audio design is described in the following sections.

Earpiece

Receiver solution is selected to be a Kirk Acoustic earpiece. Earpiece design is leak tolerant with a front protection cover directly on the earpiece component. The Earpiece will be placed in a moulded rubber gasket which seals the front cavity to the IMD Window.

In front of the earpiece and leakholes a shielding material will be placed to prevent dust particles to migrate onto the earpiece diaphragm. This material consists of a grid material type Saati PES 120/41 from Tradex (It is the same material as in Nokia 8210).

The earpiece is designed to be approved in type approval by type 3.2, low leak artificial ear (Ear Simulator Type 4195, Low Leakage). No support for type 1 artificial ear is made (Ear Simulator Type 4185).

Earpiece Acoustic Design

The earpiece is sealed to the front cover (IMD window) with a rubber gasket. The gasket is fixed inside the A-cover by the vibra motor assembly.

The Earpiece and gasket is designed to seal perfectly against the front cover. There is no

well defined leakage as known from the NPE-3 project. This is done to have a better performance in the frequency area from 2 – 3.4 kHz and to prevent the possibility of an acoustic feedback loop inside the phone mechanics.

There is no sealing between the earpiece and the PWB.

There are also holes through the PWB to make the design more leak tolerant by using the volume between PWB and the B-cover.

A-Cover or window contains front and leakage holes. On the inside of the A-cover a dust shield is placed. This shield covers both front and leakage holes.

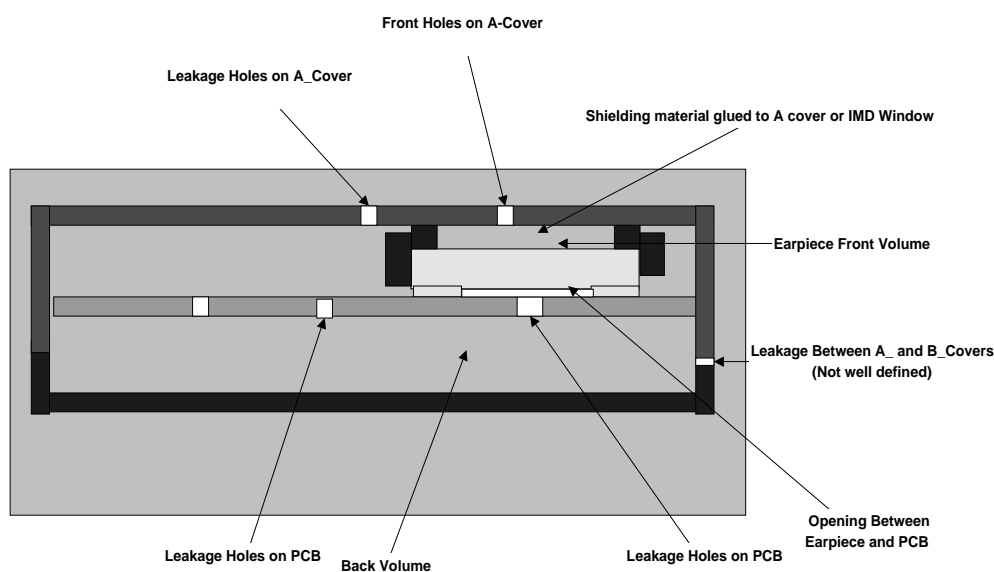


Figure 2. Sketch of Earpiece Acoustic Design

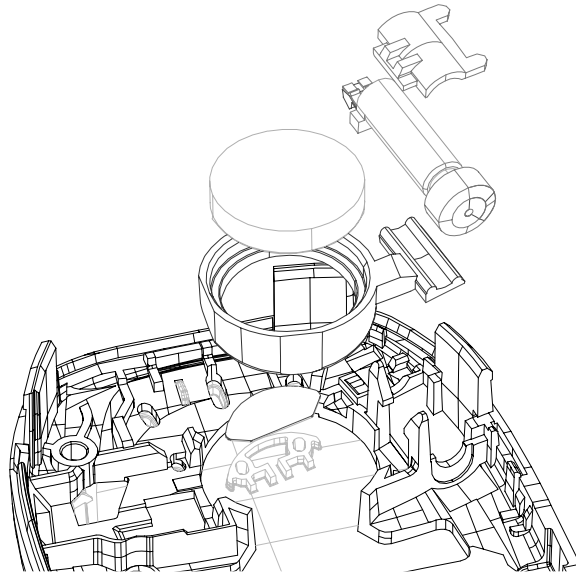


Figure 3. Mechanical assembly of Earpiece and Vibra

Specified frequency response curve for the NPL-1 design (mechanics and Audio):

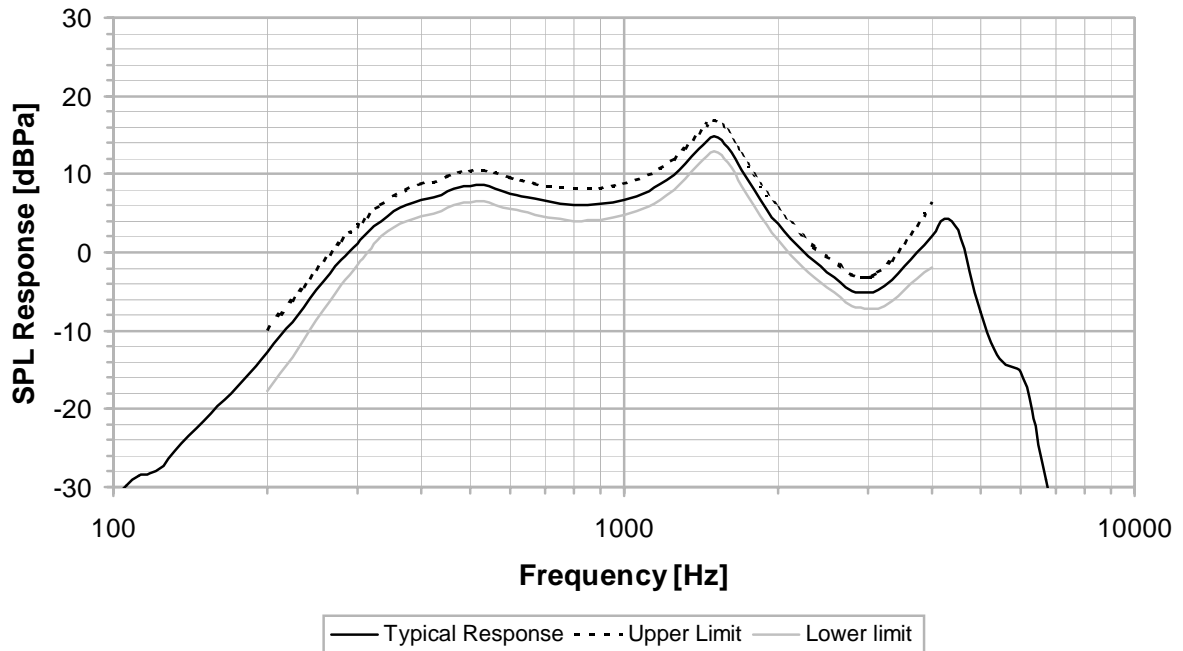


Figure 4. Earpiece frequency response - ERP corrected – non DSP corrected

Absolute Sensitivity (Low leak): 26 dBPa/V \pm 3dB @ 1kHz. (0 dB on Figure 4. Earpiece frequency response - ERP corrected – non DSP corrected)

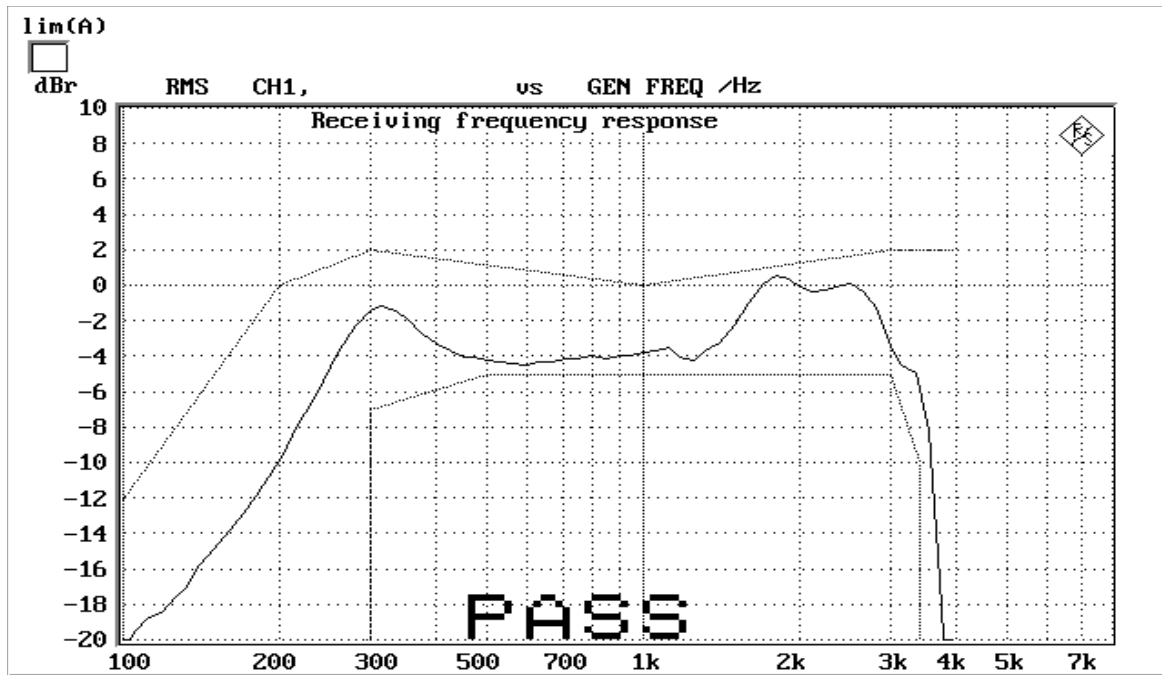


Figure 5. DAI receiving frequency response, B4.0

Earpiece Electrical Interface

Earpiece circuit includes pads for earpiece together with 2 ferrite beads (Common mode filter), 2 capacitors (900 MHz cut-off filter) and two varistors for ESD protection placed near the Earpiece.

The low impedance, dynamic type earphone is connected to the differential output (EAR) in the UEM audio CODEC. On the differential output 2 * 22 Ohm (R171) is placed for noise reduction and to compensate for the high capacitance of the varistors (1 nF), which could lead to instability in the UEM.

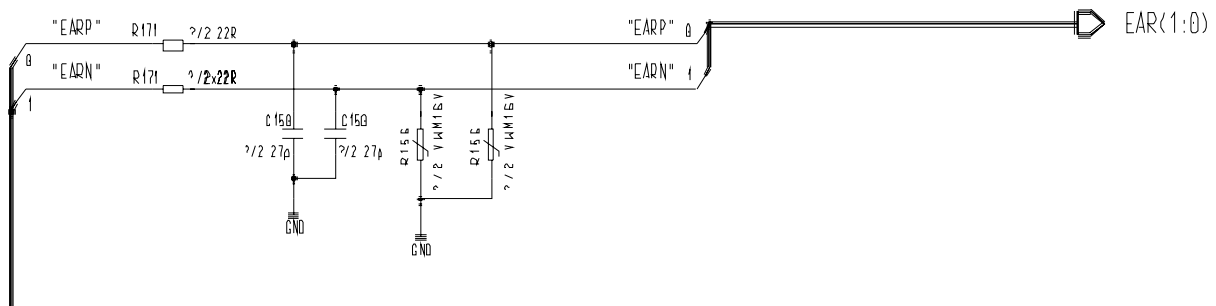


Figure 6. Internal Earpiece Electrical Interface

Ear output specifications from the UEM specifications:

Table 5: UEM Ear output specification

| Parameter | Test condition | Min | Typ | Max | Units |
|---|---|------|------|------|----------|
| Output swing @ 0dBm0, GR=-6 dB | V_{ASwing} | 2.36 | 2.5 | | V_{pp} |
| Output voltage swing | With 60 dB signal to total distortion ratio | 4.0 | | | V_{pp} |
| Output resistance | PDM data with 50 % pulse ratio in the DAC input | | | 1.0 | Ω |
| Load capacitance | EARP to EARN | | | 50 | nF |
| Load resistance | EARP to EARN | 26 | 32 | | Ω |
| Load capacitance | EARP to GND | | | 200 | pF |
| Differential offset voltage | | -50 | | 50 | mV |
| Common voltage level for EAR output (EARP & EARN) | $V_{CM_{EAR}}$ | 1.3 | 1.35 | 1.42 | V |

Microphone

An omni directional microphone (DCT3 type) is used. The microphone is placed in the system connector sealed in its rubber gasket. The sound port is provided in the system connector.

The microphone is delivered from Matsushita with the microphone mounted in the rubber gasket.

A new rubber boot (Microphone gasket) with a harder shore (shore 80 versus shore 50) will be used, to increase production ease and subsequently the production yield.

The microphone is connected to the differential input (MIC 1) of the UEM.

Sketch of Microphone Acoustic Design

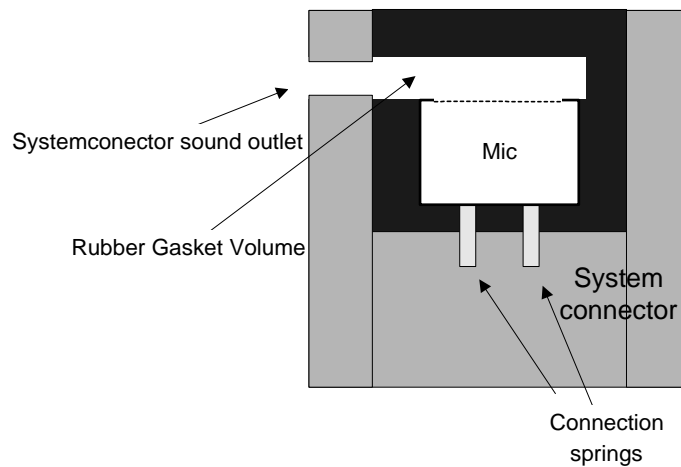


Figure 7. Microphone Acoustical Design

Absolute Sensitivity: -42 dBV/Pa ±3dB @ 1kHz.

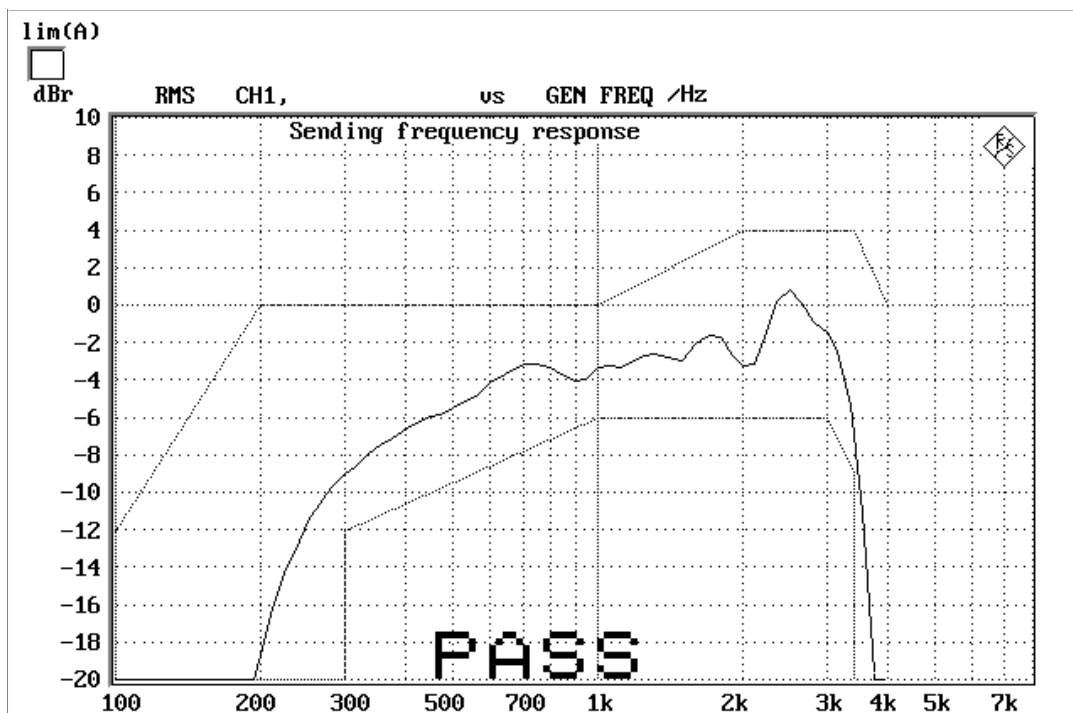


Figure 8. DAI Sending frequency response, B4.0

The desired microphone response is a flat line in 0 dB between 300 Hz and 4 kHz that roles off as much as possibly outside these frequencies.

Since the microphone response is flat, no DSP equalisation is found necessary.

Microphone Electrical Interface

The microphone electrical circuit includes 2 ferrite beads for common mode noise rejection together with 2 capacitors for filtering the 900 MHz signal and two varistors for ESD protection placed near the microphone PWB spring pads.

The 10 nF (C155) forms a low pass filter together with the microphone impedance to make a steeper roll off at high frequencies.

Also an extra High pass filter (R152 + C154) is added to limit audible TDMA-noise (217 Hz + harmonics) and to limit the bumpy road noise.

A transistor circuit (V150) on the bias line from UEM is used as the voltage supplier for minimising the noise level from the UEM bias output.

This gives an decrease in the DC voltage level across the Microphone to typically 1.1 V (1.3 V re. GND). Using Matsushita microphones as single supplier this will not pose any problems as the FET in the microphone have little variation on their V_{ds} curves.

The Microphone bias is controlled in the 8 bit AudioBiasR register. The 1 μ F (C171) is lessons learned from NPE-3 and simulations shows that this will give an even higher noise suppression. But it has the risk of oscillating. No difference has been measured on preliminary tests.

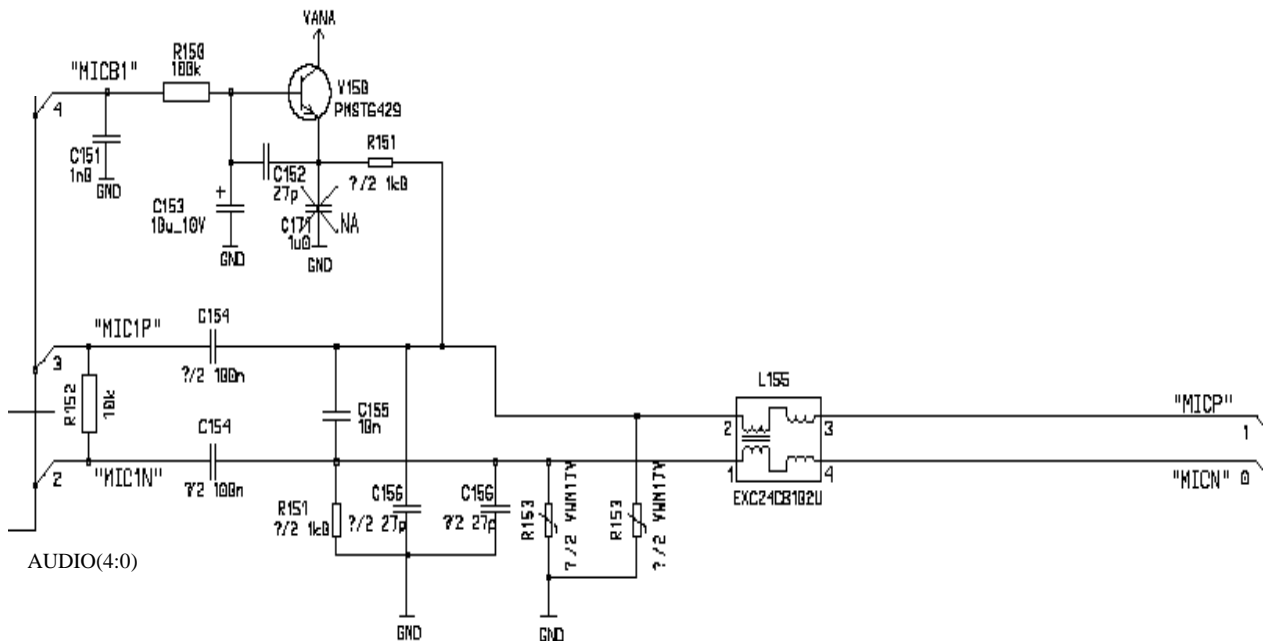


Figure 9. Internal Microphone Electrical Interface

UEM microphone input specification:

Table 6: Microphone input specifications

| Parameter | Symbol | Min | Typ | Max | Unit |
|--|------------|------|------|------|------------|
| Microphone amplifier input resistor | R_{M30} | 30 | 50 | | kOhm |
| Differential input voltage range for MIC1 input, $G = 20$ dB | V_{IN1} | | 200 | 1200 | m V_{PP} |
| Receive Common mode input voltage range for MIC input | V_{HFCM} | | 100 | | m V_{PP} |
| Common mode voltage level | V_{CM} | 1.3 | 1.35 | 1.4 | V |
| Differential mode voltage range for microphone amplifier, at gain = 20dB | V_{OUT} | | 2.0 | | V_{PP} |
| Differential load resistance for the microphone input stage | R_{OS} | 30 | | 450 | kOhm |
| Transmit gain absolute accuracy | GXA | -1.0 | | 0.0 | dB |
| Transmit gain variation with programmed gain, temperature and supply | GXAGT V | -0.7 | | 0.7 | dB |
| Common mode rejection ratio | CMRR | 45 | 60 | | dB |

Buzzer

Alerting tones and/or melodies are generated by a buzzer, which is controlled by a PWM signal from the UEM. The SPL requirement is to be as good or better than the NPE-3 in comparison test. The buzzer is delivered from the supplier with an end of line requirement of 102dB (A) at 5cm and 2.5 kHz.

The actual level is found from a comparison with NPE-3 on specific ringing tones.

The buzzer is designed to have the first resonant peak at 2500 Hz. The ringer melodies will be optimised in DSP so the main frequency of any given melody is shifted to near the resonant peak. For this optimisation a program called BuzzCalc will be used for the calculation of the dominating frequency of a given ringing melody or tone.

The design of the buzzer is a direct copy from the NPE-3 project. The Buzzer is glued to a gasket. This final assembly is delivered by STAR. Sound holes are placed in the A-cover

The A-cover is designed to give an optimal SPL by securing the tightness between buzzer and A-cover.

The buzzer is electrically connected to the PWB by spring contacts.

Buzzer Acoustic Design

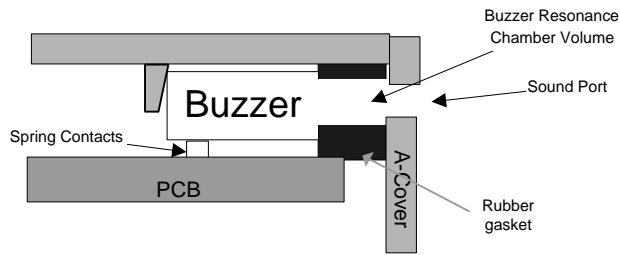


Figure 10. Sketch of Buzzer Acoustic Design

The important parameters in this design are the front cavity and the sound portholes.

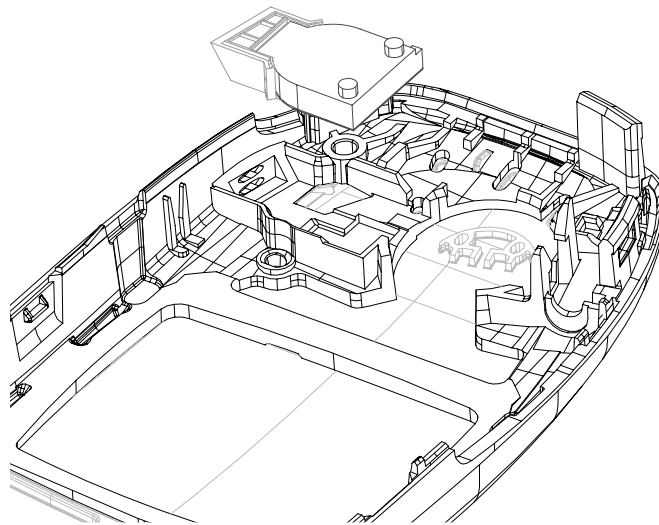


Figure 11. Mechanical buzzer assembly

The expected A weighted frequency response is (50 % Duty cycle). Tested in a simplified testbox. Final result expected to lay 2-4 dB below.

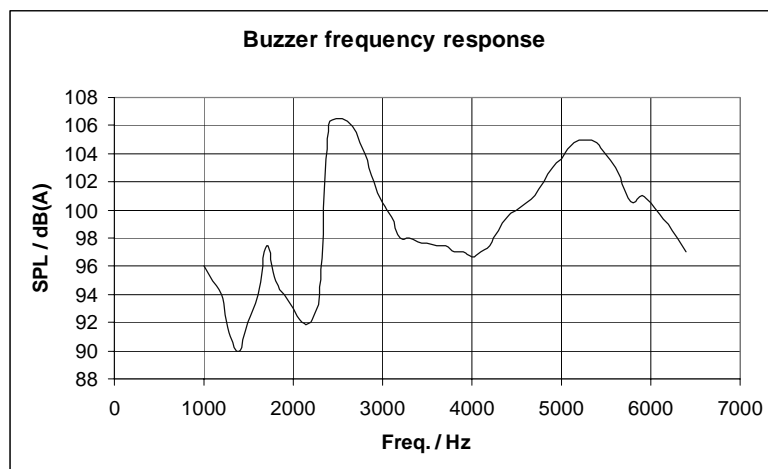


Figure 12. Typical buzzer frequency response

Buzzer Electric Interface

The driver circuit is an integral part of the UEM.

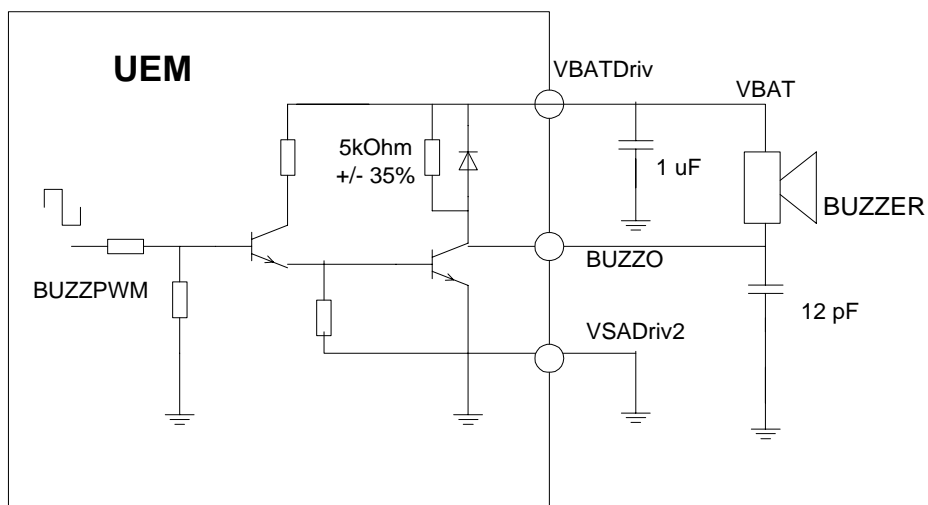


Figure 13. Buzzer driver circuit.

Table 7: Buzzer driver specifications

| Parameter | Variable | Min | Typ | Max | Unit |
|-----------------------------------|------------------|------|------|----------------------|------|
| Output switch resistance Rbuzzo | | 1.0 | 2.7 | 4.5 | Ohm |
| Output peak sink current Iout | VBAT | 120 | 180 | 350 | mA |
| Output peak sink voltage Uout | VBAT | | 0.5 | 1.2 | V |
| Output pwm duty cycle Pdcyc | | | | 50 | % |
| Buzzer coil resistance Rload | | 13 | 16 | 19 | Ohm |
| Battery voltage VBAT | Ni or Li battery | 3.03 | 3.6 | 5.2 (Ni) 4.2 (Li) | V |
| Reverse diode peak current Iforw | tp = 10 us | | | 0.35 | A |
| Output frequency Fout, GSM system | | 0.48 | 2500 | 7751 | Hz |

The buzzer is controlled from the UEM by a PWM (Pulse Width Modulated) square wave signal.

The frequency is produced by a bitstream on register BUZZFREQR that is counted through a 21 bit accumulator:

$$F_{out} = F_{BuzzClk} / ((2^{21} / BuzzFreqR) + 1)$$

BuzzClk has the same frequency as the CBusClk (1 MHz for GSM).

When buzzer DigEna = 1 then a PWM signal is present at BUZZPWM

The buzzer duty cycle is defined by:

$$\text{Duty Cycle} = \text{BPWMDCR}(5 : 0) * 0.78125\%$$

Vibra specification

A vibra alerting device is used to generate a vibration signal for an incoming call. The vibra is placed in the top of the phone. It is fastened to the A-cover by means of a rubber gasket and a lid which are pressed into the A-cover see .

The vibra is electrically connected to the PWB by spring contacts.

The vibra is controlled from the UEM by a PWM (Pulse Width Modulated) square wave signal.

Vibrator Electrical Interface

The driver circuit is an integral part of the UEM.

The two 33 nH inductors are added for decoupling the vibra motor from the RF antenna field. The two 1 nF capacitors are placed for ESD purposes.

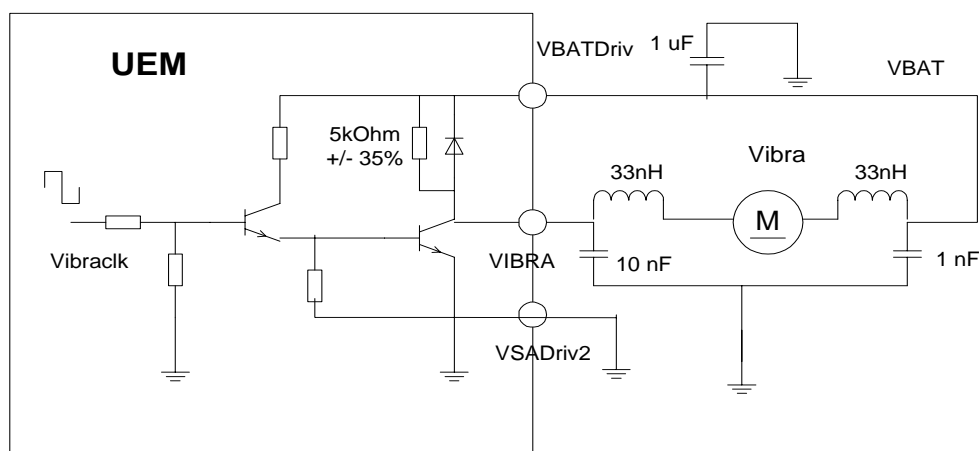


Figure 14. Vibra driver circuit

Vibra electrical specifications

Operating voltage = 1.0 V – 1.2 VDC (Controlled by the Duty cycle)

Starting Current = max 140 mA

Starting voltage = max 1 VDC

Terminal Resistance = 8.8 Ohm (typical)

Coil = 40 uH (typical)

Typical rpm: 9000 at 1.1 VDC.

Table 8: Vibra driver specifications

| Parameter | Variable | Min | Typ | Max | Unit |
|----------------------------------|--------------------|-----|-----|------|------|
| Output switch resistance Rvibra | | 1.4 | 4.2 | 7.5 | Ohm |
| Output average current Ivibra | VBAT | 50 | 80 | 135 | mA |
| Output peak current Ipeak | VBAT | | | 300 | mA |
| Output frequency Fvibra | | 64 | 129 | 520 | Hz |
| Output duty cycle Dvibra | | 2.9 | 47 | 96.9 | % |
| Reverse diode peak current lforw | tp = 10 us | | | 0.30 | A |
| Motor average dc Udc_motor | VBAT=3.0 ... 4.5 V | 1.0 | 1.5 | 2.3 | Vdc |
| Output current high imp Ihiz | V_ANA, VBAT | -1 | | 1 | uA |

Valid frequencies are: 64, 129, 258 and 520 Hz

The duty cycle of the vibra output is selected by the VCLKR register bit #7 .. #4. This is 16 accumulated duty cycles from 2.9 % to 96.9 %

The frequency of the vibra is selected by the VCLKR register bit #D1 and #D0, this clock is divided down from the 32.768 Hz clock.

Table 9: Vibra output frequency control

| D1 | D0 | Vibra output frequency |
|----|----|------------------------|
| 0 | 0 | 64,1 |
| 0 | 1 | 128,5 |
| 1 | 0 | 258,0 |
| 1 | 1 | 520,1 |

External Audio Devices

Audio Accessories

NPL-1 is supporting the following DCT3 and bluetooth audio accessories:

Headsets:

HDC-9P

Headset is the simplest audio accessory to use. It merely only consists of an earpiece, a microphone, and a switch which in technical terms is often referred to as a HOOK-switch or Headset button. The HOOK-switch can be used either to answer in-coming calls, to end a call or to initiate voice dialling calls.

The Hook interrupt is detected by software polling on the UEM hookInt input pin

HDC-9P is a purely **passive audio accessory**.

Table 10: HDC-9P interface specifications

| Object | Specification | Notes |
|------------------------------|------------------------|-------------------|
| Receiver input impedance | 150 Ohm +/- 25 % | @ 390 mV at 1 kHz |
| Maximum Sound pressure level | 106 dB SPL | at 1 mW |
| Transmitter output impedance | 2200 Ohm +/- 30 % | at 1 kHz |
| Transmitter sensitivity | - 43.5 dBV/Pa +/- 3 dB | at 1 kHz |
| XMIC bias voltage | 1.5 V | Typical |
| XMIC bias current | 1.5 mA | Maximum |

HDW-1

Bluetooth headset developed in the Tomahawk project.

The BT headset is containing a microphone, a earpiece, bluetooth module and its own audio codec. HDW-1 is battery supplied

Audio connection is full duplex digital transmission with error correction.

Table 11: Selected specifications for HDW-1 BT Headset

| | Min | Typ | Max | Unit |
|---|-----|-----|------|----------------------------|
| Ear signal in Codec after PCM DAC converter | | 80 | 490 | mVrms in codec |
| Ear signal amplifier gain in codec | -18 | 2 | 12 | dB / setting by 2 dB steps |
| Electroacoustic transfer function (Rx) | | 17 | | dBPa/V/0.5m |
| Microphone signal level | 3 | 4 | 6 | mV/Pa |
| Level at AD input in Codec | | 58 | 490 | mVrms in codec |
| Mic. amplifier gain in codec | 20 | | 42.5 | dB |
| Noise voltage, microphone | | | 5 | uVrms |

Loopsets:

LPS-1

The Loopset is a hearing aid accessory for hearing impaired persons to use mobile phones.

It consists of a **Wire-loop** and a microphone placed in a collar around the person's neck.

This is detected in the mobile as a Headset. In the UI SW it is possible to change profile from Headset to Loopset enabling the use of Loopset specific DSP tunings.

The coil amplifier is supplied from MICB2 bias voltage.

No voice dialling from the accessory is possible while there is no hookswitch (voice dialling have to be activated from the phone keypad).

Table 12: LPS-1 interface specifications

| Object | Specification | Notes |
|------------------------------|-------------------|---------------|
| Receiver input impedance | 100k Ohm +/- 5 % | Magnetic loop |
| Transmitter output impedance | 1600 Ohm +/- 30 % | at 1 kHz |
| XMIC bias voltage | 1.3 V | Maximum |
| XMIC bias current | 400 uA | Maximum |

Carkits:

CARK-91

The carkit consists of the following components:

MCC-1: Active handset holder with connection for the HFU-2 to mobile

HFU-2: Handsfree unit incl. fast charger, HF – microphone and earpiece amplifiers, interface to handset, datacard and phone and control circuit

HHS-9: Swivel mount

PCH-4J: Mounting cable

HFS-12: Handsfree earpiece, permanently installed in the car.

HFM-8: External handsfree microphone. HFM-8 is an option for the user to have a separate microphone for the carkit-installation. HFM-8 is designed to be permanently installed in a car.

The internal microphone in the mobile is muted by a MBUS message from the HFU-2 when the external microphone is detected in HFU-2.

No data call is possible in HFU-2 while DAU-9 datacable is not supported.

External accessory for Cark-91:

HSU-1: Handset unit with hookswitch. This is a handset used for private conversations without losing the link to the external antenna.

Carkit - 112

The carkit consists of the following components

HFU-1 Bluetooth junctionbox which replaces HFU-2 in the CarKit-91 setup

CUW-2 Remote control Button, earpiece volume and hookswitch

And all the components mentioned in CarKit-91 apart from HFU-2 and HSU-1.

Bluetooth CarKit developed in the Tomahawk project.

DCH-12

Handsfree Desktop Stand

The Desktop Stand is a desktop charger with integrated handsfree function.

External Audio Interface

The interface is basically a 3-wire solution, which gives two completely separate audio-paths, microphone- and earpiece-signals. The interface is split up into:

External earpiece: **XEAR** (external earpiece, single ended)

External microphone: **XMICP** (external microphone, positive)

XMICN (external microphone, negative)

External Audio Interface – Electrical Interface

The external audio connections are presented in Figure 15. External Microphone Interface and The hookInt is pulled up by 47 kOhm and the detection is being polled by software on GENIO2 via the Inverter circuit. A 100k Ohm resistor is added to the HookInt line to avoid DC-clicks in the Uplink path.. A headset or a handsfree unit can be connected directly to the system connector. The headset microphone bias is supplied from UEM MICB2 output and fed to the microphone through XMICP line.

Note: MIC3 lines will be disconnected from MIC2 and grounded near the UEM.

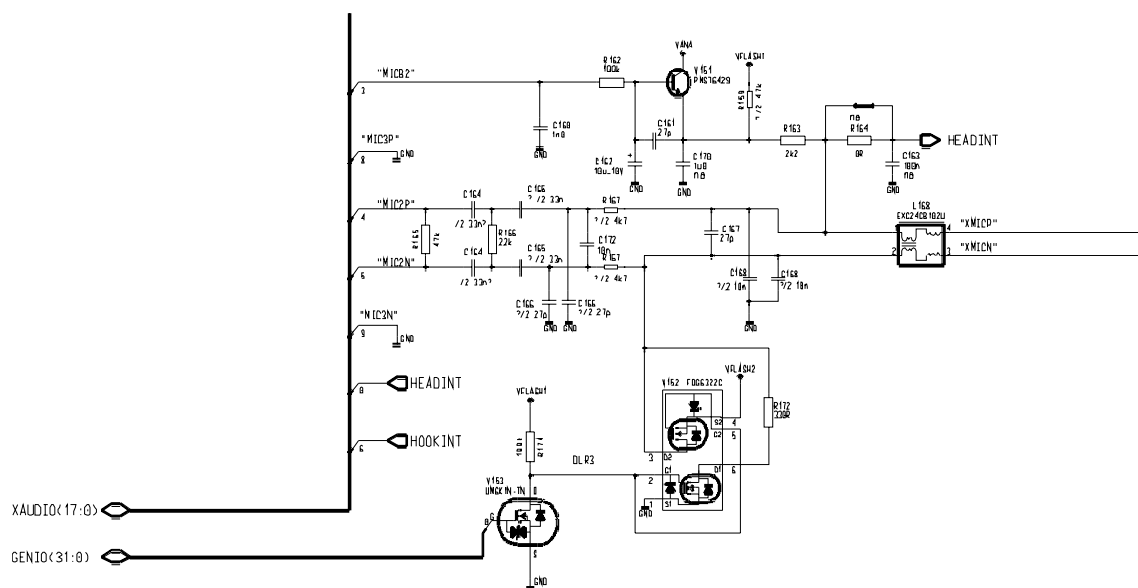


Figure 15. External Microphone Interface

See Table 13. Microphone input specifications, external audio for the input specifications for the external microphone.

The external audio interface microphone electrically circuit includes 2 ferrite beads for common mode rejection together with 2 capacitors for filtering the 900 MHz signal.

An extra Lowpass filter (R167 and C172) for a steeper roll-off at higher frequencies and two high pass filters (C165 and R166, C164 and R165) are added to limit the audible TDMA-noise and to improve bumpy road noise suppression.

A transistor circuit on the bias line from UEM is used for a voltage supplier for minimising the noise level from the UEM bias output.

The Microphone bias is controlled in the 8 bit AudioBiasR register.

When DLR-3 cable is not connected there is a 330 Ohm pulldown resistor from SGND (XMICN) to L-GND (R172). When DLR-3 is connected Vflash2 voltage of 2.78 V is used as supply for the data cable on SGND line.

Connections for MIC3 are grounded near the UEM and not as shown in Figure 15. External Microphone Interface connected to MIC2 lines.

Table 13: Microphone input specifications, external audio

| Parameter | Symbol | Min | Typ | Max | Unit |
|---|--------------------|------|------|------|-------------------|
| Microphone amplifier gain for MIC 2 / Handsfree | MicG2 | 0 | | 22,5 | dB |
| Microphone amplifier gain for MIC 2 / Headset | MicG2 | 22.5 | | 42,5 | dB |
| Microphone amplifier input resistor | R _{MIC} | 30 | 50 | | kOhm |
| Differential input voltage range for MIC2 input, G =20 dB | V _{IN2} | | 200 | | m V _{PP} |
| Differential input voltage range for MIC2 input, G =0 dB | V _{IN2} | | 2.0 | | V _{PP} |
| Receive Common mode input voltage range for MIC input | V _{INCMR} | | 100 | | m V _{PP} |
| Common mode voltage level | V _{CM} | 1.3 | 1.35 | 1.4 | V |
| Differential mode voltage range for microphone amplifier, gain 20 dB | V _{OUT} | | 2.0 | | m V _{PP} |
| Differential load resistance for the microphone input stage | R _{GS} | 30 | | 450 | kOhm |
| Transmit gain absolute accuracy | GXA | -1.0 | | 0.0 | dB |
| Transmit gain variation with programmed gain, temperature and supply | GXAGTV | -0.7 | | 0.7 | dB |
| Common mode rejection ratio | CMRR | 45 | 60 | | dB |

From the UEM output a Boomer circuit is added to give enough output swing to the headset. The boomer is coupled as differential input single ended output. The differential input is using HF / HFCM output from the UEM.

The Boomer is controled by UPP GENIO14. This control signal enables and disables the boomer wich have a internal circuit for uptimal and clickfree startup.

The boomer timing is mostly controled by C176. The nearly clickless operation has been made by timing in the MCU SW (A 12 msec delay between UEM and Bommer startup and a 1 sec delay between boomer and UEM shutdown has be made.)

The Gain of the circuit is controled by R176 / R 180 and R177 / R 178. Leading to a Boomer HW gain of approximately 3 dB.

Filtering in the boomer circuit:

Highpass: -3dB point = 234 Hz

Lowpass: -3dB point = 3386 Hz

The 15 Ohm with a load of 150 Ohm reduce the output level with approximately 0.8 dB.

XEAR circuit includes 1 ferrite bead HF filter, 1 capacitor (900 MHz cut-off filter) and one 10 nF capacitor (C181) placed near the system connector for EMC purposes.

On the single ended output 15 Ohm (R183) is placed to compensate for the high capacitance of the 10 nF condensator, which could lead to instability in the Boomer.

The hookInt is pulled up by 47 kOhm and the detection is being polled by software on GENIO2 via the Inverter circuit. A 100k Ohm resistor is added to the Hookint line to avoid DC-clicks in the Uplink path.

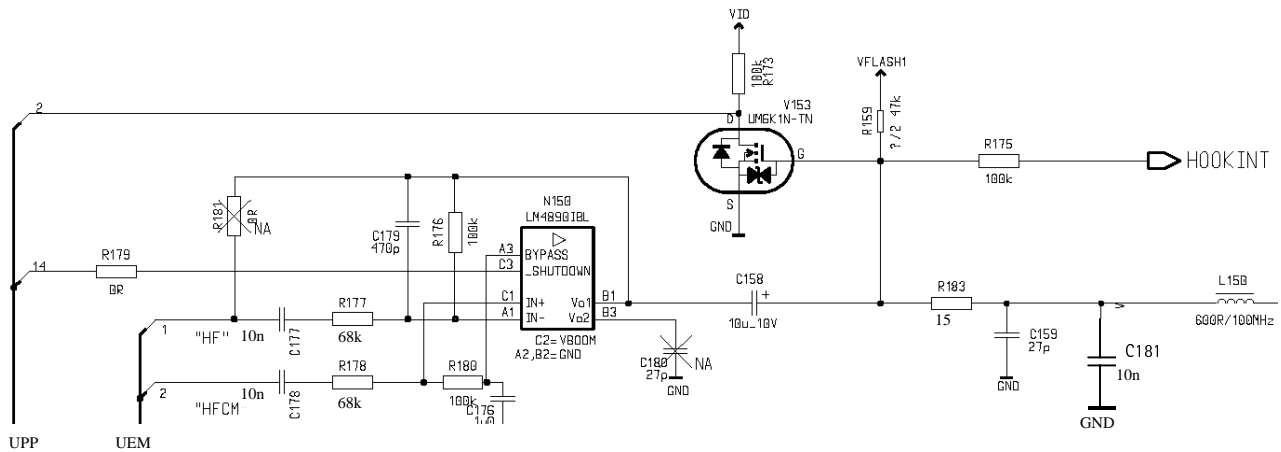


Figure 16. External Earpiece Interface

Table 14: UEM HF output specifications

| Parameter | Test condition | Min | Typ | Max | Unit |
|--|---|-----|-----|-----|-----------------|
| Output voltage swing single ended mode | with 60 dB signal to total distortion ratio | 1.0 | | | V _{PP} |
| Output voltage swing fully differential mode | with 60 dB signal to total distortion ratio | 2.0 | | | V _{PP} |
| Output resistance (0 Hz to 4 kHz) | PDM Data with 50 % pulse ratio in the DAC input | | | 1 | Ohm |
| Parasitic load resistance | HF to HFCM (with external audio circuitry) | | | 10 | nF |
| Load resistance | HF to HFCM or VSA (with headset) | 30 | | 45 | Ohm |

Table 14: UEM HF output specifications

| Parameter | Test condition | Min | Typ | Max | Unit |
|--|----------------|------|-----|------|------|
| Offset voltage | | -50 | | 50 | mV |
| Common voltage level for HF output (HF and HFCM) | $V_{CM_{HF}}$ | 0.75 | 0.8 | 0.85 | V |
| Pull down resistor value in HF output | R_{PD} | 3 | 10 | 25 | kOhm |
| Pull down switch resistance in HFCM output | R_{SW} | | | 400 | Ohm |

HEADINT and **HOOKINT** are 'interrupts input' in UEM.

Headint is used to identify the type of accessory that is connected to the system connector. The interrupt is generated by pulldown resistors in the respective accessories.

Hookint is used for detecting the hook switch of the headset.

HF is the audio output through which audio can be routed to either Headset-earpiece or Carkit earpiece. HF is wired as single ended output, which in reality performs the audio-amplification.

MIC2P, MIC2N, MIC3P and **MIC3N** are all inputs to the microphone amplifier in the UEM. In short form the main difference for the listed inputs are:

MIC2P, MIC2N: Rated to audio signals up to 2 Vpp (with gain 0 dB). Used for Headset and Carkit microphone.

MIC3P, MIC3N: Rated to audio signals up to 2 Vpp (with gain 0 dB). Used for FM Radio

Both types of inputs can be wired and used to either fully differential or singled-ended operation, however the fully differential configuration is chosen for the DCT3 interface.

External Audio Connector

The accessibility to the external audio interface is reached by the system connector.

The configuration for the bottom connector is shown in the following figure.

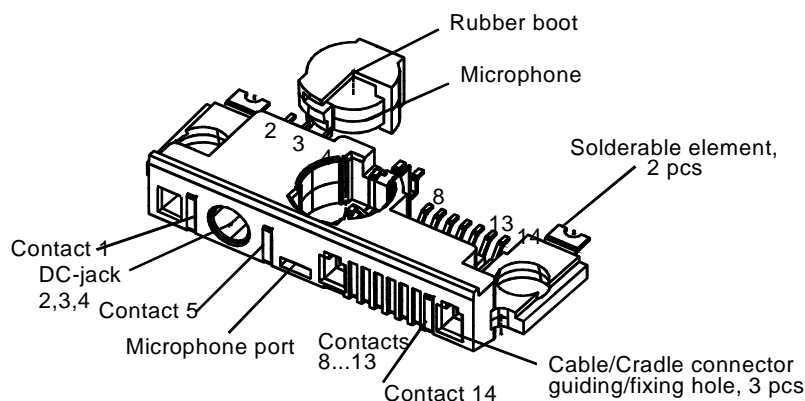


Figure 17. System connector – mechanical outline

External Audio Signal Electrical Specification

Table 15: System connector pin assignment

| Pin | Name | Min | Typ | Max | Unit | Notes |
|-----|------------|-----|-------|------|----------------|--|
| 1 | VIN | 0 | | 8.5 | V | Unloaded Fast Charger Supply current |
| | | 0 | | 850 | mA | |
| | | 0 | | 16.9 | Vpeak | Unloaded Standard Charger |
| | | 1.0 | Apeak | | Supply current | |
| 2 | L-GND | 0 | 0 | 0 | V | Supply ground DC Jack |
| 3 | VIN | 0 | | 8.5 | V | Unloaded Fast Charger DC Jack Supply current |
| | | 0 | | 850 | mA | |
| 4 | CHRG_ CTRL | 0 | | 0.8 | V | Charger control (PWM) <i>dig. Low</i> DC Jack Charger control (PWM) <i>dig. High</i> |
| | | 1.7 | | 2.9 | | |
| | | 1 | 32 | 37 | Hz | PWM frequency for a fast charger |
| | | 1 | | 99 | % | PWM duty cycle |
| 5 | CHRG_ CTRL | 0 | | 0.8 | V | Charger control (PWM) <i>dig. Low</i> Bottom charger contacts Charger control (PWM) <i>dig. High</i> |
| | | 1.7 | | 2.9 | | |
| | | 1 | 32 | 37 | Hz | PWM frequency for a fast charger |
| | | 1 | | 99 | % | PWM duty cycle |
| 6 | MICP | 0 | 2 | 100 | mV | Connected to UEM MIC1P input. (re. SGND) |
| 7 | MICN | 0 | 2 | 100 | mV | Connected to UEM MIC1N input. (re. SGND) |

Table 15: System connector pin assignment

| Pin | Name | Min | Typ | Max | Unit | Notes |
|-----|---------|-----|------|------|-------------------------------------|--|
| 8 | XMIC | 2.0 | | 2.2 | k Ω | Input AC impedance |
| | | | | 1 | Vpp | Maximum signal level |
| | | 0 | | 1.55 | V | Mute (output DC level) |
| | | 2.5 | | 2.9 | V | Unmute (output DC level) |
| | | 100 | | 600 | μ A | Bias current from UEM |
| | | | | 2 | Vpp | Microphone signal (Gain 0 dB) Connected to UEM MIC3P + MIC2P input |
| 9 | SGND | | 330 | | Ω | Resistance to phone ground, return path for XMIC. When the DLR-3 data cable is connected, SGND switches to be a supply line for the cable (2.8V) |
| 10 | XEAR | | 47 | | Ω | Output AC impedance (ref. LGND) |
| | | | 10 | | μ F | Series output capacitance |
| | | 16 | | 300 | Ω | Load AC impedance to GND (Headset) pin #14 |
| | | 4.7 | 10 | | k Ω | Load AC impedance to GND (Accessory) pin #14 |
| | | | 1.0 | | Vpp | Maximum output level (no load) |
| | | | 6.8 | | k Ω | Load DC resistance to GND (Accessory) pin #14 |
| | | 16 | | 1500 | Ω | Load DC resistance to GND (Headset) pin #14 |
| | 2.78 | 2.8 | 2.86 | V | DC voltage (47k pull-up to Vflash1) | |
| | HEAR | 0 | 14 | 220 | mV | Earphone signal Connected to UEM HF output |
| 11 | MBUS | 0 | | 0.8 | V | Serial bi-directional control bus. Baud rate 9600 Bit/s Phone has 4.7k Ω pull up resistor in UEM |
| | | 2.0 | | 2.8 | | |
| 12 | FBUS_RX | 0 | | 0.8 | V | Fbus receive. Serial Data Baud rate 9.6k-230.4kBit/s Phone has 220k Ω pull down resistor |
| | | 2.0 | | 2.8 | | |
| 13 | FBUS_TX | 0.1 | | 0.8 | V | Fbus transmit. Serial Data Baud rate 9.6k-230.4kBit/s Phone has 47k Ω pull up resistor in UEM |
| | | 1.7 | | 2.8 | | |
| 14 | L-GND | 0 | | 0 | V | Supply ground |

Accessory Detection, Identification and Control

Accessory Detection

Accessories are detected when the XMIC signal is loaded with either DLR3, Loopset or Headset. The interrupt is generated by pulldown resistors in the respective accessories.

Carkit 91 is detected via communication on the MBUS line.

BT accessories are connected after BT connectivity is chosen in UI. Communication with UEM is done over the CBUS lines.

Accessory Identification

The voltage on the XMICP is used to identify which type of accessories that are connected to the system connector. See Table 16: HEADINT Voltage Value Table used for Accessory Identification. The HEADINT interrupt is detected in the UEM and this voltage level is used to determine the type of accessory.

A voltage is measured on the HeadInt input on the UEM. This signal is multiplexed to an A/D converter in the UEM. From this level an Accessory server recognises the type of accessory and chooses the relevant audio accessory tuning if applicable. If the detection voltage window is as described in Table 16: HEADINT Voltage Value Table used for Accessory Identification for headset and loopset the microphone bias is enabled.

If DLR3 is used the detection voltages are as in Table 16: HEADINT Voltage Value Table used for Accessory Identification, no bias for the microphone is enabled and 2.8 V DC for DLR3 is supplied.

Table 16: HEADINT Voltage Value Table used for Accessory Identification

| ACCESSORY CONNECTED | HEADINT VOLTAGE LEVEL | | NOTES |
|----------------------------------|-----------------------|--------|--|
| | MIN | MAX | |
| Headset HDC-9P and Loopset LPS-1 | 19 mV | 300 mV | Without MBias Varying with microphone FET working line. |
| Carkit CARK-91 | | | Detected and acknowledged by the phone on MBUS |
| DLR3 | 300 mV | 800 mV | |

Accessory Control

Headset and Loopset

In the HDC-9P the headset-button is electrically connected across the XEAR and L-GND lines. When the Headset button is activated, XEARP is short-circuited to L-GND and a HOOKINT interrupt is detected in the UEM. This is used to lift the receiver, to put it down or initiate voice call.

HDW-1 is a Bluetooth Headset. The BT headset is recognised by the phone after a BT search for any BT component in the vicinity has been performed and a connection is set up via the BT module in both phone and accessory.

In case of BT audio the BT accessory and the phone is connected by both an ACL and SCO air link. ACL is used for connection commands and SCO for the actual audio transmission. In both cases the BT module (in accessory and phone) receives the audio signal. In the phone this signal is routed from BT module over LPRF to DSP where it follows the regular audio path through out the rest of the system. The BT module and MCU is connected by the CBUS for exchanging low level information.

Carkit

CARK-91

The carkit communicates with the phone through the system connector via the MBUS lines. No interrupts are detected on the HeadInt or HookInt. HeadInt is disabled so a voltage on the XMIC line is not able to initiate the interrupt. All communication is controlled in the HFU-2 unit. Voice dialling is only possible in CARK-91 via phone "name" softkey.

The HFU-2 sends an MBUS registration messages to the phone when the HFU-2 is powered up. This message includes an identification number for the HFU-2 box. The phone will send an acknowledge message and communication are set-up.

The HFU-2 box includes power amplifier for Earpiece (nom. gain 26 dB) and preamplifier for Microphone (nom. gain 30 dB).

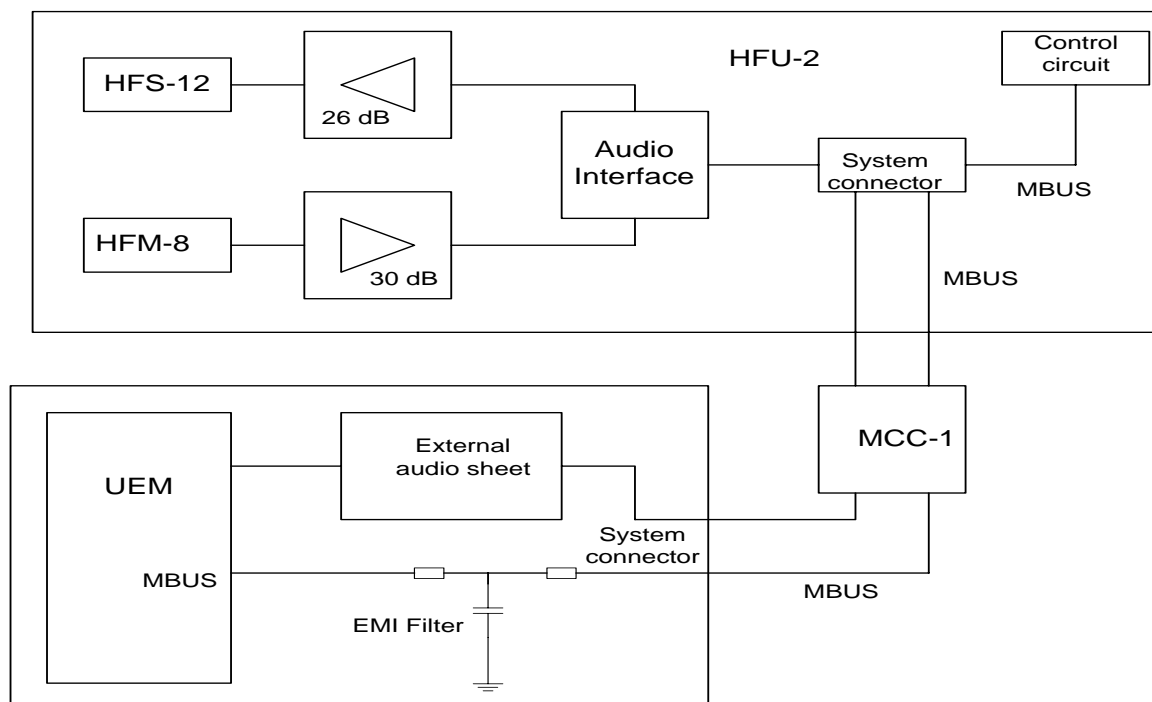


Figure 18. Carkit audio interface. Block diagram.

CARK-64

This carkit is a passive kit and is just a holder for the phone. No detection is done anywhere.

CARK-112

This is a Bluetooth carkit. The BT Carkit is recognised by the phone after a BT search for any BT component in the vicinity has been performed and a connection is set up via the BT module in both phone and accessory.

In case of BT audio the BT accessory and the phone is connected by both an ACL and SCO air link. ACL is used for connection commands and SCO for the actual audio transmission. In both cases the BT module (in accessory and phone) receives the audio signal. In the phone this signal is routed from BT module over LPRF to DSP where it follows the regular audio path through out the rest of the system. The BT module and MCU is connected by the CBUS for exchanging low level information.

Voice dialling is only possible in CARK-112 via phone "name" softkey.

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